



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-10-17
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9679PTR	AAYE*UAI3BBP	A	MUAR B/E	2016-10-17
Amount		UoM	Unit type	ST ECOPACK Grade
520		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	100	gull wing	
Comment	TQFP 100 14x14x1.0 1.0 ExpadDown			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

ELV directive : 2000/53/EC amended 2016/774 _May 2016	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AAVE*UAI3BBP									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	25.082	mg	supplier	die	Silicon (Si)	7440-21-3		22.520	mg	897855	43308				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	2111	102				
				supplier	metallization	Copper (Cu)	7440-50-8		1.386	mg	55259	2665				
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	80	4				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	359	17				
				supplier	metallization	Tungsten (W)	7440-33-7		0.079	mg	3150	152				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.172	mg	6858	331				
				supplier	metallization	Platinum (Pt)	7440-06-4		0.097	mg	3867	187				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	1794	87				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.346	mg	13795	665				
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.013	mg	518	25				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.034	mg	1356	65				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.064	mg	2552	123				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	120	6				
				supplier	polymer die coating	Polyimide AH 1200	Proprietary		0.259	mg	10326	498				
				Leadframe	Copper & its alloys	221.483	mg	supplier	alloy	Copper (Cu)	7440-50-8		210.198	mg	949048	404227
								supplier	alloy	Nickel (Ni)	7440-02-0		6.555	mg	29596	12604
supplier	alloy	Magnesium (Mg)	7439-95-4						0.328	mg	1481	631				
supplier	alloy	Silicon (Si)	7440-21-3						1.420	mg	6411	2731				
supplier	metallization	Nickel (Ni)	7440-02-0						2.731	mg	12331	5252				
supplier	metallization	Palladium (Pd)	7440-05-3						0.142	mg	641	273				
supplier	metallization	Gold (Au)	7440-57-5						0.077	mg	348	149				
supplier	metallization	Silver (Ag)	7440-22-4						0.032	mg	144	62				
Die attach	Other Organic Materials	5.777	mg	supplier	glue	Silver (Ag)	7440-22-4		5.171	mg	895101	9944				
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.433	mg	74953	833				
				supplier	glue	Bismaleimide resin	35325-39-4		0.173	mg	29946	333				
Bonding wires	Other inorganic materials	0.986	mg	supplier	wire	Copper (Cu)	7440-50-8		0.986	mg	1000000	1896				
				Encapsulation	Other Organic Materials	266.672	mg	supplier	mold compound	Silica, vitreous	60676-86-0		230.405	mg	864001	443087
supplier	mold compound	Epoxy Resin	25068-38-6					20.000	mg	74996	38462					
supplier	mold compound	Phenol Resin	29690-82-2					13.334	mg	50001	25642					
supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0					1.333	mg	5002	2563					
supplier	mold compound	Quartz	14808-60-7					0.800	mg	3000	1538					
				supplier	mold compound	Carbon black	1333-86-4		0.800	mg	3000	1538				